



**SPECTRA7 WELCOMES LINEAR TECHNOLOGY CO-FOUNDER BOB DOBKIN
AS DIRECTOR AND INVESTOR**

Revered Industry Guru To Work Closely With Management and Board

March 20, 2013 – Palo Alto, CA and Toronto, ON – (TSX-V: SEV) Spectra7 Microsystems Inc. (“Spectra7”), a high performance analog semiconductor company delivering unprecedented speed, resolution and signal fidelity to consumer and wireless infrastructure products, officially welcomed Robert (Bob) Dobkin as an investor and member of the Board of Directors.

“Throughout his illustrious career, Bob’s had an enormous impact on how the analog semiconductor marketplace has evolved; as evidenced by the immense success of Linear Technology, which he co-founded in 1981,” commented Tony Stelliga, CEO of Spectra7. “We’re thrilled to welcome Bob as both an investor and member of the Board and look forward to his guidance and mentorship as we continue to build Spectra7 into a world-class organization.”

Mr. Dobkin has over thirty-five years experience in analog design and has developed many advanced products at National Semiconductor (“National”) and Linear Technology (“Linear”). In 1981, he co-founded Linear, has served as Vice President of Engineering and Chief Technical Officer since April 1999, and as Vice President of Engineering from September 1981 to April 1999. From January 1969 to July 1981, he was employed in various positions at National, where his most recent position was Director of Advanced Circuit Development.

Mr. Dobkin attended the Massachusetts Institute of Technology.

“I’ve known Tony for years and was intrigued at Spectra7’s ability to combine performance and speed with system-level knowledge,” commented Dobkin. “This is a new frontier for the analog marketplace and I’m excited be part of this young, dynamic and rapidly growing company.”

ABOUT SPECTRA7 MICROSYSTEMS INC.

Spectra7 Microsystems Inc. (TSX-V: SEV) is a high performance analog semiconductor company delivering unprecedented speed, resolution and signal fidelity to consumer and wireless infrastructure products. Spectra7's new system level components address the bottlenecks and the exponential demand for more bandwidth and lower costs in mobile and internet infrastructure equipment, including handsets, tablets, base stations and microwave backhaul systems. For more information, please visit www.spectra7.com.

Certain information in this news release may constitute forward-looking information. This information is based on current expectations that are subject to significant risks and uncertainties that are difficult to predict. Actual results might differ materially from results suggested in any forward-looking statements. Spectra7 assumes no obligation to update the forward-looking statements, or to update the reasons why actual results could differ from those reflected in the forward-looking statements unless and until required by securities laws applicable to Spectra7. Additional information identifying risks and uncertainties is contained in Spectra7's filings with the Canadian securities regulators available at www.sedar.com.

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